

Amendments to the Claims

1. (Currently Amended) A tape substrate comprising:

an insulating film;

a copper foil pattern formed on the insulating film at one side of the insulating film, and provided with a connecting area where an electronic element is to be mounted;

a barrier layer, made of a compound, which contains gold and silver as major components thereof and an additive of Se or Pb, plated on the copper foil pattern at the connecting area, and formed with a plurality of pores; and

a tin layer plated on the barrier layer, and alloyed with a portion of the copper foil pattern corresponding to the connecting area, through the pores.

2-4. (Canceled)

5. (Original) The tape substrate according to claim 1, wherein the barrier layer has a thickness of 0.01 to 1 μ m.

6. (Original) The tape substrate according to claim 1, wherein the tin layer has a thickness of 0.01 to 1 μ m.

7-13. (Canceled)